Korean International Semiconductor Conference & Exhibition
on Manufacturing Technology 2025

KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

[WeB1] HARC Etch and Plasma Source

Session Date	November 12 (Wed.), 2025
Session Time	09:00-10:40
Session Room	Room B (Grand Ballroom 1, 2F)

[WeB1-1] [Invited] 09:00-09:30

Next Generation HARC Etch Technologies Requiring Ultra-High Aspect Ratio, High Selectivity, and Very High Etch Rate for VNAND Device

Kyujin Jang, Hoki Lee, and Jaeho Min (Samsung Electronics Co., Ltd., Korea)

[WeB1-2] [Invited] 09:30-09:55

3D NAND Dielectric Etch Technology Challenges and Breakthroughs

Dongsoo Lee (Lam Research Korea, Korea)

[WeB1-3] 09:55-10:10

Advanced Etch Technology Using Ultra-Low Electron Temperature Plasma

Junyoung Park, Nayeon Kim, Min-Seok Kim, and Chin-Wook Chung (Hanyang Univ., Korea)

[WeB1-4] 10:10-10:25

Investigation of Toroidal Slot Antennas for Microwave Heating and Plasma Generation

Sung-Hyeon Jung and Ho-Jun Lee (Pusan Nat’l Univ., Korea)

[WeB1-5] 10:25-10:40

Investigation of Plasma Density Distribution and Electron Heating Mechanisms in Capacitively Coupled Plasma

Seong Eun Oh and Ho-Jun Lee (Pusan Nat'l Univ., Korea)